

SMD LED LAMP
BL-LS3014A0S1
Features:

- 3.0mmx1.4mm SMD, 0.7mm THICKNESS PLCC2 package
- Mono-color type, Ultra brightness
- Compatible with automatic placement equipment
- WIDE VIEWING ANGLE.
- IDEAL FOR BACKLIGHT AND INDICATOR.
- PACKAGE: 3KPCS/REEL
- RoHs Compliance


Electrical-optical characteristics: (Ta=25°C) (Test Condition: IF=30mA)

Part Number	Chip			Lens Type	Forward Voltage(VF) Unit:V		Luminous Intensity (Iv) Unit:mcd		Viewing Angle 2θ(1/2(deg))
	Emitted Color	Material	λ _P (nm)		Typ	Max	Min.	Typ.	
BL-LS3014A0S1UEC	Ultra Red	AlGaAs	630	Water Clear	2.10	2.50	350	520	120
BL-LS3014A0S1UYO	Ultra Amber	AlGaInP	610		2.10	2.60	600	900	
BL-LS3014A0S1UYC	Ultra Yellow	AlGaInP	593		2.10	2.60	600	900	
BL-LS3014A0S1UGC	Ultra Green	AlGaInP	575		2.20	2.70	350	600	
BL-LS3014A0S1PGC	Ultra Pure Green	InGaN	525		3.00	3.40	1500	1800	
BL-LS3014A0S1UBC	Ultra Blue	InGaN	470		3.00	3.40	850	1000	
BL-LS3014A0S1UWC	Ultra White	InGaN	/		3.00	3.40	2500	3000	
BL-LS3014A0S1UW2C	Warm White	InGaN	/		3.00	3.40	2300	2800	

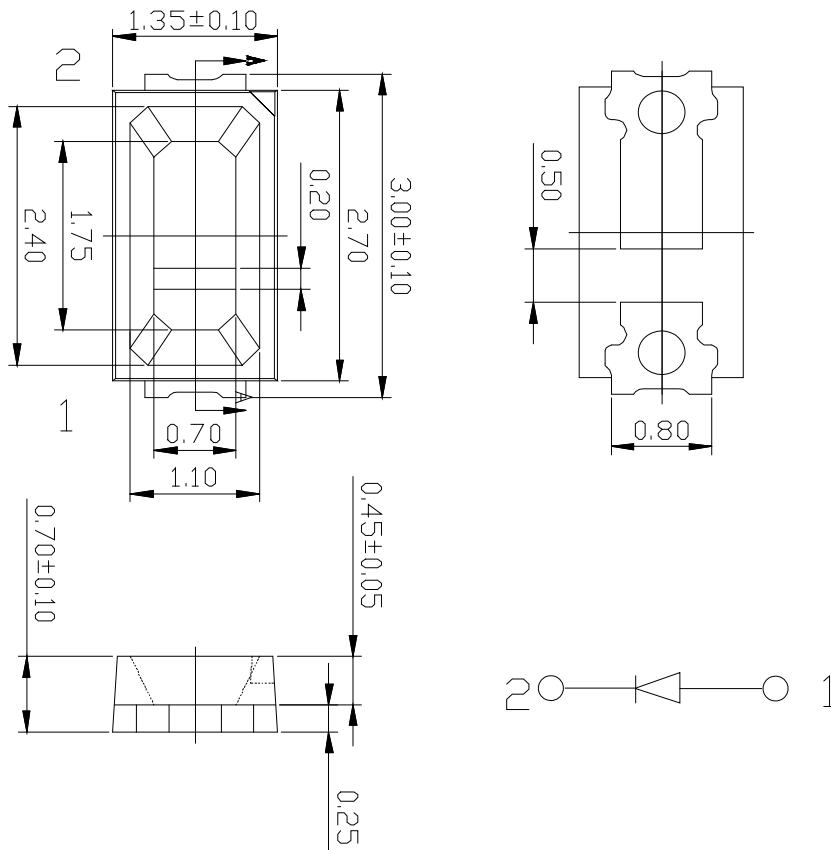
Absolute maximum ratings (Ta=25°C)

Parameter	UE	UYO	UY	UG	PG	UB	UW	Unit
Forward Current I _F	30	30	30	30	30	30	30	mA
Power Dissipation P _d	66	66	66	66	66	66	66	mW
Reverse Voltage V _R	5	5	5	5	5	5	5	V
Peak pulsing current (1/8 duty f=1KHz) I _{fp}	40	40	40	40	40	40	40	mA
Operation Temperature T _{OPR}	-25 to +80							°C
Storage Temperature T _{STG}	-30 to +85							°C
Lead Soldering Temperature T _{SOL}	Max.260±5°C for 3 sec Max. (1.6mm from the base of the epoxy bulb)							°C

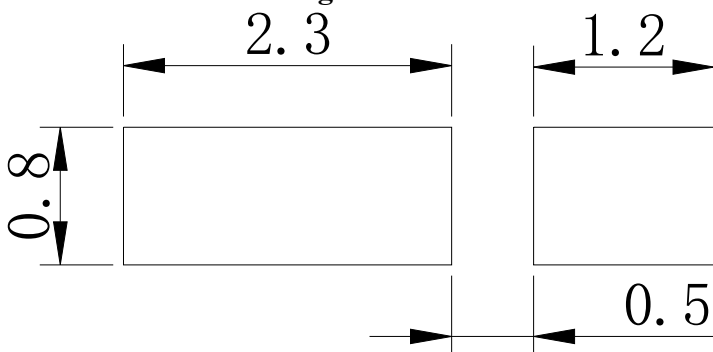
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■ **Package configuration & Internal circuit diagram**



Recommended Soldering Patter



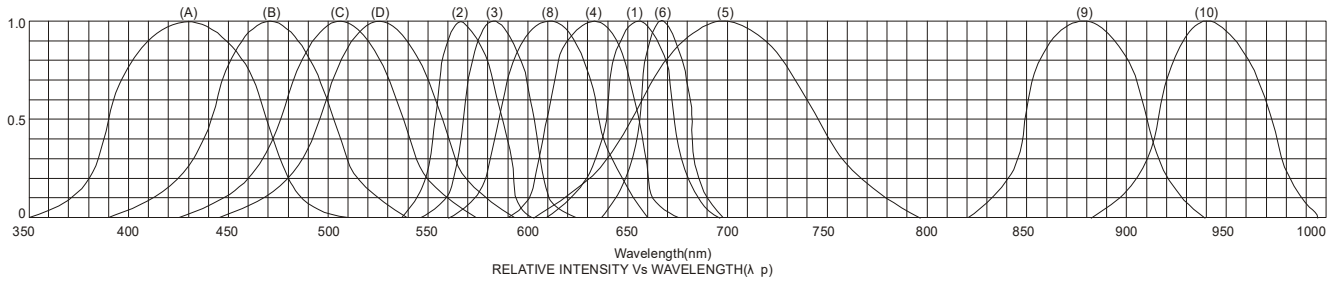
Notes:

1. All dimensions are in millimeters (inches)
2. Tolerance is ±0.25(0.01")unless otherwise noted.
3. Specifications are subject to change without notice.

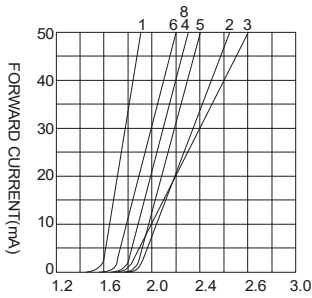
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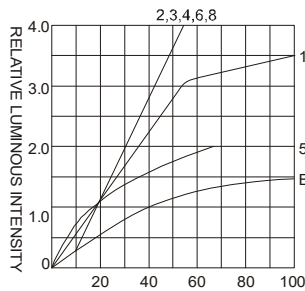
■ **Typical electrical-optical characteristics curves:**



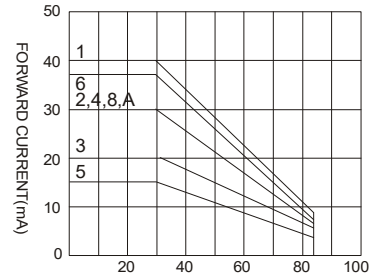
- (1) - GaAsP/GaAs 655nm/Red
- (2) - GaP 570nm/Yellow Green
- (3) - GaAsP/GaP 585nm/Yellow
- (4) - GaAsP/GaP 635nm/Orange & Hi-Eff Red
- (5) - GaP 700nm/Bright Red
- (6) - GaAlAs/GaAs 660nm/Super Red
- (8) - GaAsP/GaP 610nm/Super Red
- (9) - GaAlAs 880nm
- (10) - GaAs/GaAs & GaAlAs/GaAs 940nm
- (A) - GaN/SiC 430nm/Blue
- (B) - InGaN/SiC 470nm/Blue
- (C) - InGaN/SiC 505nm/Ultra Green
- (D) - InGaN/SiC 525nm/Ultra Green



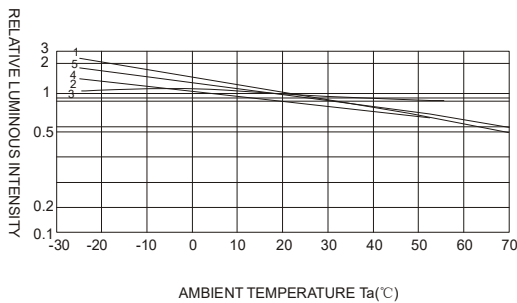
FORWARD VOLTAGE (Vf)
FORWARD CURRENT VS.
FORWARD VOLTAGE



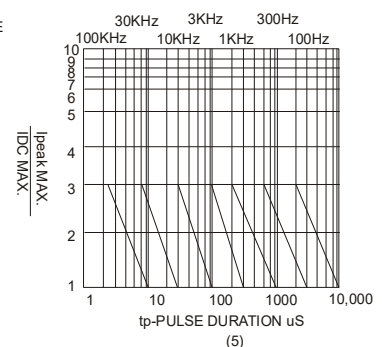
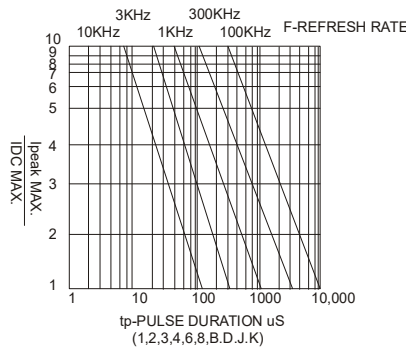
FORWARD CURRENT (mA)
RELATIVE LUMINOUS
INTENSITY VS. FORWARD
CURRENT



AMBIENT TEMPERATURE Ta(°C)
FORWARD CURRENT VS. AMBIENT
TEMPERATURE



AMBIENT TEMPERATURE Ta(°C)



NOTE:25°C free air temperature unless otherwise specified

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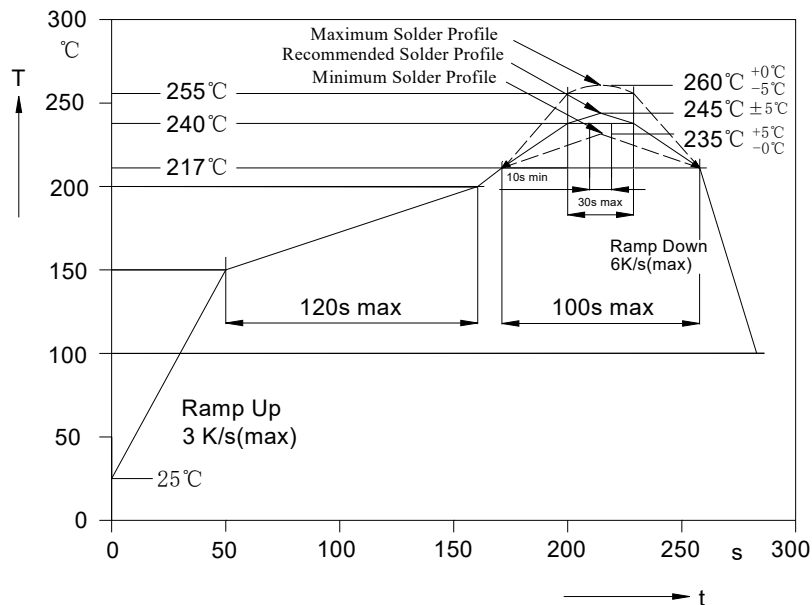
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Guideline for Soldering

Reflow Soldering:

Use the conditions shown in the under Figure of Pb-Free Reflow Soldering.

SMD-Reflow Soldering Profile for lead free soldering(Acc.to J-STD-020B)



Hand Soldering

1) A soldering iron of less than 20W is recommended to be used in Hand Soldering Please keep the temperature of the soldering iron under 360°C while soldering Each terminal of the LED is to go for less than 3 second and for onetime only.

2) Be careful because the damage of the product is often started at the time of the hand soldering

Cleaning

1)It is recommended that alcohol be used as a solvent for cleaning after soldering. Cleaning is to go under 30°C for 3 minutes or 50°C for 30 seconds. When using other solvents, it should be confirmed beforehand whether the solvents will dissolve the package and the resin or not.

2) Ultrasonic cleaning is also an effective way for cleaning. But the influence of Ultrasonic cleaning on LED depends on factors such an ultrasonic power. Generally, the ultrasonic power should not be higher than 300W.Before cleaning, a pre-test should be done to confirm whether any damage to LEDs will occur.

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■ **Packing and weighting**

